

SEMICONDUCTING DEVICE WITH FOLDED INTERPOSER

Abstract of the Disclosure

Some embodiments of the present invention relate to a semiconducting device that includes an interposer having a fold which divides the interposer into a first section and a second section. A first die is attached to a first surface of the interposer at the first and second sections of the interposer. The semiconducting device further includes a contact that is attached to the first surface of the interposer at the first section and the second section. A second die is attached to a second surface of the interposer such that the second die is stacked onto the first die and is electrically coupled to the first die by the contact and conductive paths that are part of the interposer.

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